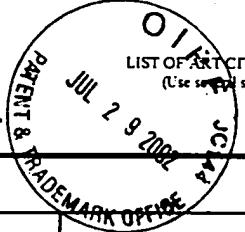


Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-1684	SERIAL NO. 09/827,248		
				APPLICANT David Hembree			
				FILING DATE April 4, 2001	GROUP 2838		
U.S. PATENT DOCUMENTS							
*Examiner Initial	Document Number	Date	Name	Class	Subclass		
VN	AA 5,612,574	3/18/97	Summerfelt et al.				
	AB 5,719,333	2/17/98	Hosoi et al.				
	AC 5,831,333	11/3/98	Malladi et al.				
	AD 5,919,548	7/6/99	Barron et al.				
	AE 5,351,283	9/3/96	Manaka et al.				
V	AF 5,492,011	2/20/96	Amano et al.				
	AG						
	AH						
	AJ						
FOREIGN PATENT DOCUMENTS							
	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
	AK						
	AL						
	AM						
	AN						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AB	"JTC and PTG Thermistors"; <a href="http://www.thermedics.com/intro.htm">http://www.thermedics.com/intro.htm</a> ; 1/7/00; 3 pages.					
	AR	"DI-5B35 Linearized 4-Wire RTD Input"; <a href="http://www.dataq.com/di5b35.htm">http://www.dataq.com/di5b35.htm</a> ; 1/7/00; 3 pages.					
	AS	"RTD"; <a href="http://www.micrsensors.com/rtds.htm">http://www.micrsensors.com/rtds.htm</a> ; 1/7/00; 3 pages.					
	AT	"Low Cost Thermal Ribbon (TM) uses thin film RTDF"; <a href="http://www.mince.com/c17634ar.htm">http://www.mince.com/c17634ar.htm</a> ; 1/7/00; 1 page.					
	AU	"Silicon Processing for the VLSI Era"; Volume I - Process Technology, Second Edition; S. Wolf et al.; 2000; pp. 23-25 and pp. 841-845.					
EXAMINER <i>Paul Nguyen</i>		DATE CONSIDERED <i>10/18/2002</i>					
<p>"EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant."</p>							

Form PTO-1449  O I P E JAN 28 2002 SJC35				U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-1684		SERIAL NO. 09/827,248	
				APPLICANT David R. Hembree					
				FILING DATE April 4, 2001		GROUP 2829			
U.S. PATENT DOCUMENTS									
*Examiner Initial	TRADEMARK OFFICE	Document Number	Date	Name		Class	Subclass	Filing Date If Appropriate	
VN		AA 3,440,407	4/22/69	Golstos et al.					
		AB 3,614,345	10/19/71	Quinn					
		AC 3,683,306	8/8/72	Bulthuis et al.					
		AD 4,332,081	6/1/82	Francis					
		AE 4,518,944	5/21/85	Faris					
		AF 4,703,555	11/3/87	Hubner					
		AG 5,141,334	8/25/92	Castles					
		AH 5,347,869	9/20/94	Shie et al.					
		AI 5,406,109	4/11/95	Whitney					
		AJ 5,430,646	7/25/95	McArthur et al.					
		AK 5,446,437	8/29/95	Bantien et al.					
FOREIGN PATENT DOCUMENTS									
		Document Number	Date	Country		Class	Subclass	Translation	
		AL 3336778	7/1/97	France				Yes	No
		AM 56-12521	2/1981	Kobayashi, Japan					
		AN 2-268462	11/1990	Yamanishi, Japan					
		AO							
		AP							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)									
	AR	Application Guide Temperature Sensors, Welsco Electrical Manufacturing Company Catalog, pp. 771-778, 1992/1993.							
	AS	In-Situ Survey System of Resistive and Thermoelectric Properties of Either Pure or Mixed Materials in Thin Films Exposed Under Ultra High Vacuum, Lecherwiller, Lithovac, Richen, Sauer, A. Compt. 1 Phys. III Electron., Vol. 6, pp. 409-418, 04/05 (Abstract only).							
	AT-	Temperature Metrology for CD Control in DUV Lithography, Jeffrey Parker and Wayne Berkman, pp. 111-112, 114, 116, 00/17/07.							
EXAMINER <i>nh Nguyen</i>				DATE CONSIDERED 10/18/2002					
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.									

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-16804	PRIORITY SERIAL NO. 09/137,629		
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT David R. Hembree			
		JUL 29 2002 U.S. PATENT DOCUMENTS		PRIORITY FILING DATE August 21, 1998	PRIORITY GROUP 2858		
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	4,560,216	12/24/85	Egawa			
	AB	4,754,555	7/5/98	Sillman			
	AC	5,475,317	1/5/99	Smith			
	AD	5,495,667	3/5/96	Farnsworth et al.			
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AE	S.N. 09/032,184; Filed 2/22/98; Alkram et al.; Amendment filed 12/18/00; CPA filed 7/28/00; Amendment filed 3/9/00; Amendment filed 8/23/00;  <u>Original Application filed 7/7/97; 20 claims</u>					
	AF	Advertisement for Probe Technology: <a href="http://www.idinet.com">www.idinet.com</a> ; Interconnect Devices, Inc.; 1 page; 3/6/98					
	AG	Good Things Come in Small BGA/CSP Packages; <a href="http://www.johnstech.com/47/handbook/page0.html">www.johnstech.com/47/handbook/page0.html</a> ; 1 page; 3/5/98					
	AH	Product Description for Double Ended Probes, B1052 Series; <a href="http://www.testprobe.com/products/b1052.html">www.testprobe.com/products/b1052.html</a> ; Rika Denshi America, Inc.; 1 page; 2/4/98					
	AI	Product Description for Test Centers, RM-500 Series Probes; <a href="http://www.testprobe.com/products/rm500.html">www.testprobe.com/products/rm500.html</a> ; Rika Denshi America, Inc.; 1 page; 2/4/98					
	AJ	Product Description for Cost Effective Interconnections for High I/O Products; <a href="http://www.testprobe.com/products/i0.htm#b1303">www.testprobe.com/products/i0.htm#b1303</a> ; Rika Denshi America, Inc.; 1 page; 2/4/98					
	AK	Product Description for Ball Grid Probe B1303-C3; <a href="http://www.testprobe.com/products/i0.htm#b1303">www.testprobe.com/products/i0.htm#b1303</a> ; Rika Denshi America, Inc.; 1 page; 2/4/98					
	AL	Product Description for Test Socket Contacts; <a href="http://www.johnstech.com/47/handbook/page0.html">www.johnstech.com/47/handbook/page0.html</a> ; 1 page; 3/5/98					
<u>EXAMINER</u> <i>rmh/Nguye</i>		<u>DATE CONSIDERED</u> <i>03/10/03</i>					
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

Form PTO-1449  LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE  JUL 29 2002 S1A PATENT & TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-1684	SERIAL NO. 09 327,248	
				APPLICANT David R. Hembree				
				FILING DATE April 4, 2001		GROUP 2829	2829	
<b>PATENT DOCUMENTS</b>								
*Examiner Initial		Document Number	Date	Name		Class	Subclass	Filing Date If Appropriate
	AA	3,440,467	4/2/69	Gobos et al.				
	AB	3,614,345	10/19/71	Quinn				
	AC	3,683,306	8/2/73	Bulthius et al.				
	AD	4,112,081	6/1/82	Frances				
	AE	4,118,944	5/21/83	Faris				
	AF	4,703,555	11/1/87	Hubner				
	AG	5,141,934	8/25/92	Castles				
	AH	5,347,969	9/20/94	Shie et al.				
	AI	5,406,100	4/11/95	Whitney				
	AJ	5,416,646	7/25/95	McAllister et al.				
	AK	5,446,437	8/20/95	Bartels et al.				
<b>FOREIGN PATENT DOCUMENTS</b>								
		Document Number	Date	Country		Class	Subclass	Translation
VN	AL	2336778	7/1977	France				Yes
VN	AM	56-12521	2/1981	Kobayashi, Japan				No
VN	AN	2-268462	11/1990	Yamazishi, Japan				
	AO							
	AP							
<b>OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)</b>								
VN	AR	Application Guide Temperature Sensors, Wadlow Electrical Manufacturing Company Catalog, pp. 775-778, 1992/1993. (month unavailable)						
VN	AS	In-Situ Survey System of Resistive and Thermoelectric Properties of Either Pure or Mixed Materials in Thin Films Evaporated Under Ultra High Vacuum, Lechevalier, Lehmer, Richou, Sarron, & Gouani, J. Phys. III France, Vol. 3, pp. 409-418, 04/93 (Abstract only).						
VN	AT	Temperature Metrology for CD Control in DUV Lithography, Jeffrey Parker and Wayne Reeken, pp. 111-112, 114, 116, 09/17/97.						
EXAMINER <i>Mark Nguyen</i>				DATE CONSIDERED 03/10/03				
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE  LIST OF ARTS CITED BY APPLICANT (Use separate sheet if necessary)		ATTY. DOCKET NO. MI22-1684		SERIAL NO. 09/327,248		
				APPLICANT David Hembree		FILING DATE April 4, 2001		GROUP 2829
U.S. PATENT DOCUMENTS								
*Examiner Initial		Document Number	Date	Name		Class	Subclass	Filing Date If Appropriate
	AA	5,612,574	3/18/97	Summerich et al.				
	AB	5,719,333	2/17/98	Nasoi et al.				
	AC	5,831,333	11/9/98	Mahdavi et al.				
	AD	5,819,548	7/6/99	Baron et al.				
	AE	5,851,283	9/3/96	Mantika et al.				
	AF	5,492,011	2/20/90	Amano et al.				
	AG							
	AH							
	AJ							
FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country		Class	Subclass	Translation
	AK							Yes
	AL							No
	AM							
	AN							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
VN	AP		"NTC and PTC Thermistors"; <a href="http://www.thermodisc.com/ntcptc.html">http://www.thermodisc.com/ntcptc.html</a> ; 1/7/98; 2 pages.					
VN	AR		"DI-5B35 Linearized 4-Wire RTD Input"; <a href="http://www.dataq.com/d5b35.html">http://www.dataq.com/d5b35.html</a> ; 1/7/98; 2 pages.					
VN	AS		"RTD"; <a href="http://www.mtsensors.com/rtds.html">http://www.mtsensors.com/rtds.html</a> ; 1/7/98; 3 pages.					
VN	AT		"Low Cost Thermal-Ribbon (TM) uses thin film RTD"; <a href="http://www.minco.com/s17624nr.html">http://www.minco.com/s17624nr.html</a> ; 1/7/98; 1 page.					
VN	AU		"Silicon Processing for the VLSI Era"; Volume I - Process Technology, Second Edition; S. Wolf et al.; 2000; pps 22-25 and pps. 841-845.					
EXAMINER <i>mh Nguyen</i>		DATE CONSIDERED <i>03/10/03</i>						
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								